

FEATURES

- Widely used in all kinds of battery packs
- High degree of inrush current capability
- Precise melting time
- Surface mount technology allows fuses to be directly attached to printed circuit boards
- Notebook Computer
Wireless Base Station
Networking
Telecom System
- Significant savings in weight and real estate
- RoHS / REACH / AEC-Q200

RS PRO, Fuse, Ceramic SMD LTCC Chip Fuse, Fast Acting, 10A-30A, 1206

RS Stock No.: 2522161
2522162



RS Professionally Approved Products bring to you professional quality parts across all product categories. Our product range has been tested by engineers and provides a comparable quality to the leading brands without paying a premium price.

Surface Mount Fuse — LTCC Chip Fuse

Product Description

Ceramic SMD LTCC Chip Fuse, Fast Acting, 10A-30A, 1206

Applications:

- Notebook Computer
- Wireless Base Station
- Networking
- Telecom System
- Battery Management System (Battery Pack)

General Specifications

Current Rating	10A, 12A, 15A, 20A, 25A	30A
Voltage Rating	63V	48V
Body Material	Ceramic	
Interrupting Ratings	10A – 25A	100A @ 63V DC 250A @ 24V DC
	10A – 30A	200A @ 36V DC 150A @ 48V DC
	30A	300A @ 24V DC
Operating Temperature	-55°C to +125°C	
Country of Origin	Taiwan	

Electrical Characteristics

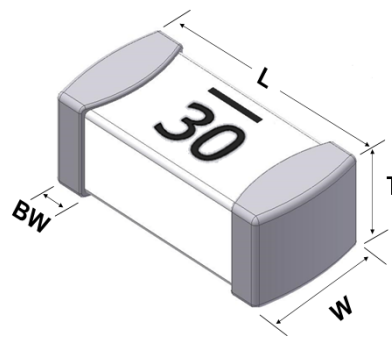
Rated Current	Opening Time	
	1 In Min.	3.5 In Max.
10A-30A	4 hr	5 sec

I²t Nominal Cold Resistance & I²t & Safety Approval:

Approvals	Marking	Interrupting rating		Nominal Cold Resistance (Ohms)	Nominal Melting I ² t (A ² sec.)
10A	$\overline{10}$	100A @ 63V DC 200A @ 36V DC 250A @ 24V DC	*	0.0038 - 0.0070	14
12A	$\overline{12}$		*	0.0028 - 0.0052	19
15A	$\overline{15}$		*	0.0023 - 0.0043	33
20A	$\overline{20}$		*	0.0014 - 0.0026	56
25A	$\overline{25}$		*	0.0012 - 0.0022	182
30A	$\overline{30}$	150A @ 48V DC 200A @ 36V DC 300A @ 24V DC	*	0.0009 - 0.0017	260

Shape & Dimension:

Type	1206
L	3.1 ± 0.2 mm
W	1.6 ± 0.2 mm
T	0.9 ± 0.2 mm
BW	0.5 ± 0.25 mm



Recommended Pad Layout	
L1	1.10 mm
L2	1.52 mm
W	1.78 mm

